

Class HC equivalent die up-screening

MIL-PRF-19500 JANHC Equivalent Up-Screening Rev. R		
Screening Requirements		
Test	Quantity (Accept Number of Failures)	MIL-STD-750
Subgroup 1: Electrical Test (DC1)	100%	As per Electrical Datasheet
Subgroup 2: Visual Inspection	100%	2069, 2070, 2072, 2073
Subgroup 3A: Internal/Die Visual Inspection	10 (0)	2069, 2070, 2072, 2073
Subgroup 3B: Sample Assembly	10 minimum	
Subgroup 4A: Temperature Cycling	10 (0)	1051-C, 20 Cycles
Subgroup 4B: Electrical Test as per Datasheet: DC Test @ 25°C / DC Test @ -55°C / DC Test @ 150°C / AC Test @ 25°C (DC2-DC4), (AC1)	10 (0)	As per Electrical Datasheet
Subgroup 4C: HTRB	10 (0)	1038-A, 1039-A, 1042-B, 48 Hours (PNP 24 Hours), 80% Rated V _R , T _A = 150°C
Subgroup 4D: Electrical Test (DC5)	10 (0)	As per Electrical Datasheet
Subgroup 4E: Burn-In/SSOP	10 (0)	1038-B, 1039-B, 1042-A, 160 Hours (Diode 96 Hours), T _J = Max Junction Temperature
Subgroup 4F: Electrical Test as per Datasheet: DC Test @ 25°C (DC6)	10 (0)	As per Electrical Datasheet
Subgroup 5A: Wire Pull	10 Wires (0) or 20 Wires (1)	2037, 1 Hour 300°C Pre-Test Bake (Bimetallic Bonds only)
Subgroup 5B: Die Shear	5(0) or 10 (1)	2017

Note: Devices supplied will be to the test flow illustrated above. Any changes to the flow must be agreed upon in writing by the customer and Central Semiconductor Corp.